



ERSO83-002B

Application no. 10/061,023

2814

March 11, 2003

TO: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Attn: Art Unit 2814 - Examiner Dilinh P Nguyen

FROM: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 10/061,023
File Date: Jan 30, 2002
Inventor: SM Chang
Examiner: Dilinh P Nguyen
Art Unit: 2814
Title: Composite Bump Bonding

6/Election
SM Chang
3-22-03
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RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

This is in response to the Restriction Requirement in the Office Action dated Feb. 11, 2003. In that office action, restriction was required to one of the following Inventions under

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on Mar. 11, 2003.

Signature 
Stephen B. Ackerman, Reg. No. 37,761

Date: Mar. 11, 2003

35 U.S.C. 121:

The inventions stated are:

I - Claims 1-6, drawn to a method of a semiconductor device, classified in class 257, subclass 678, and

II - Claims 7-20, drawn to a method for making a semiconductor device, classified in class 438, subclass 106.

This Restriction Requirement was sent in error. Claims 7-20 have already been cancelled from this Divisional application, please see the original filing papers submitted on the Filing date of Jan. 30, 2002.

Please examine the remaining claims 1-6.

Withdrawal of the Restriction Requirement, and allowance of the present Patent Application, is respectfully requested.

It is requested that should there be any problems with this response, please call the undersigned Attorney at (845) 452-5863.

Respectfully submitted,



Stephen B. Ackerman, Reg. No. 37,761